Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

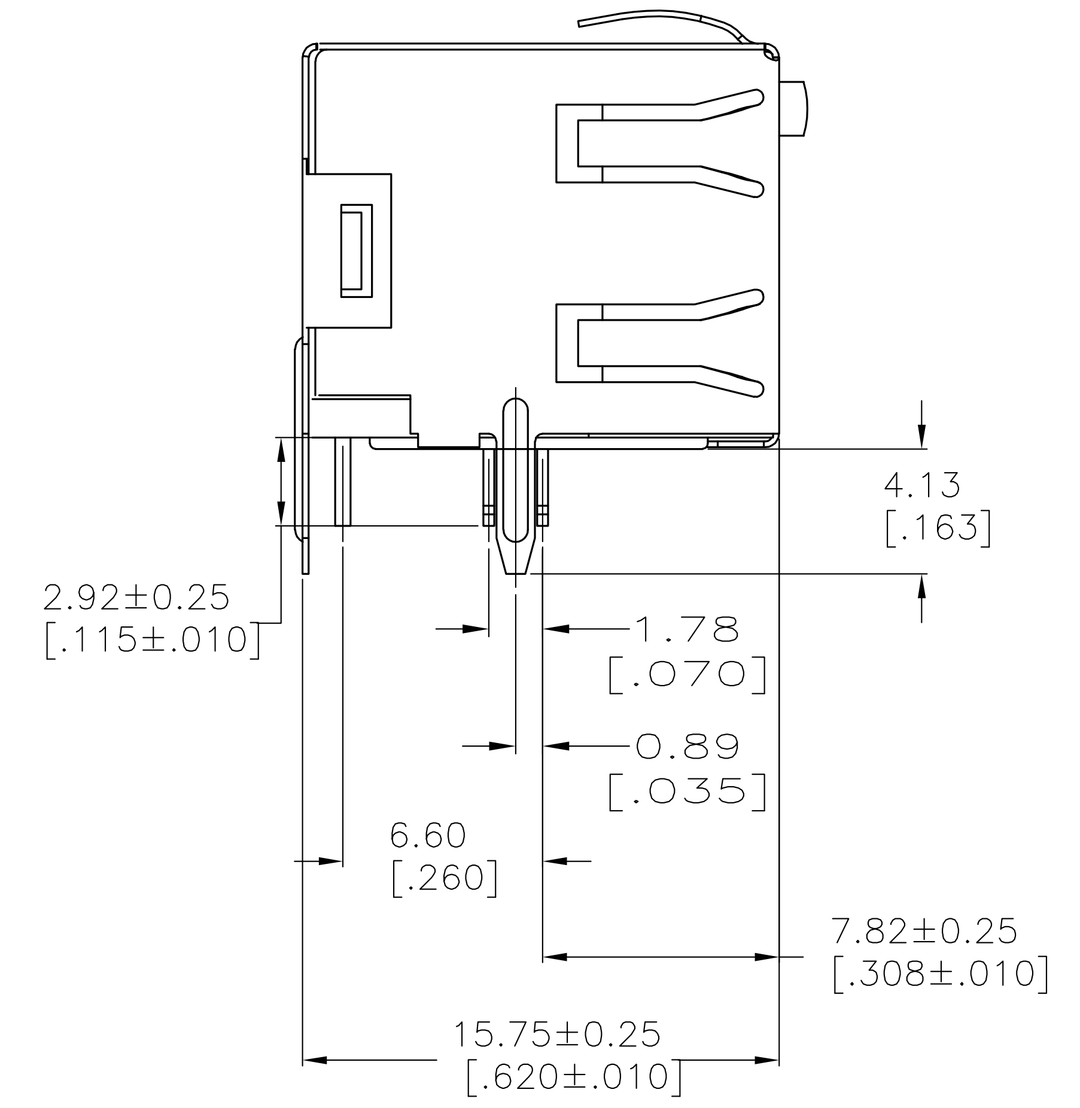
With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

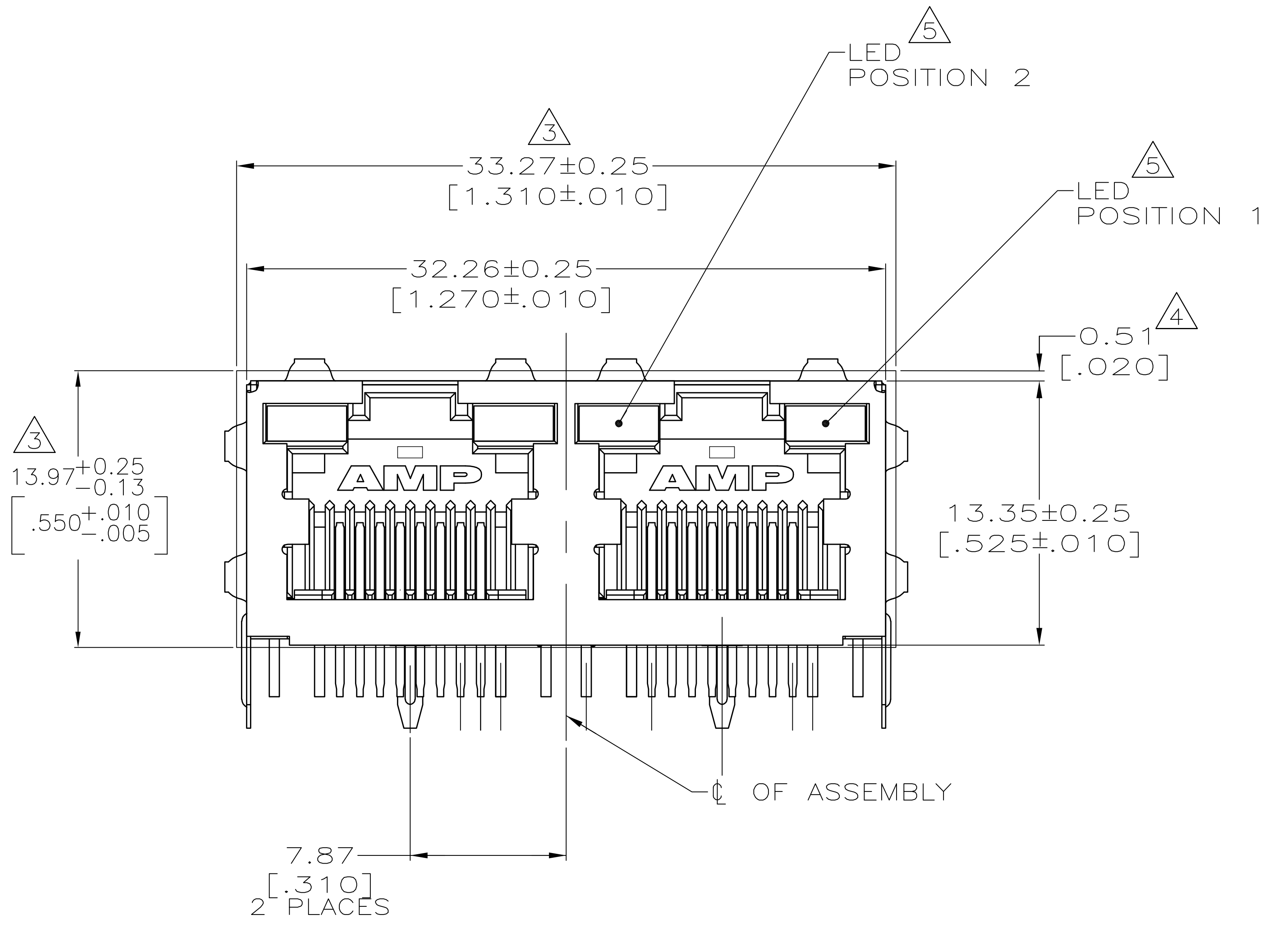
We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

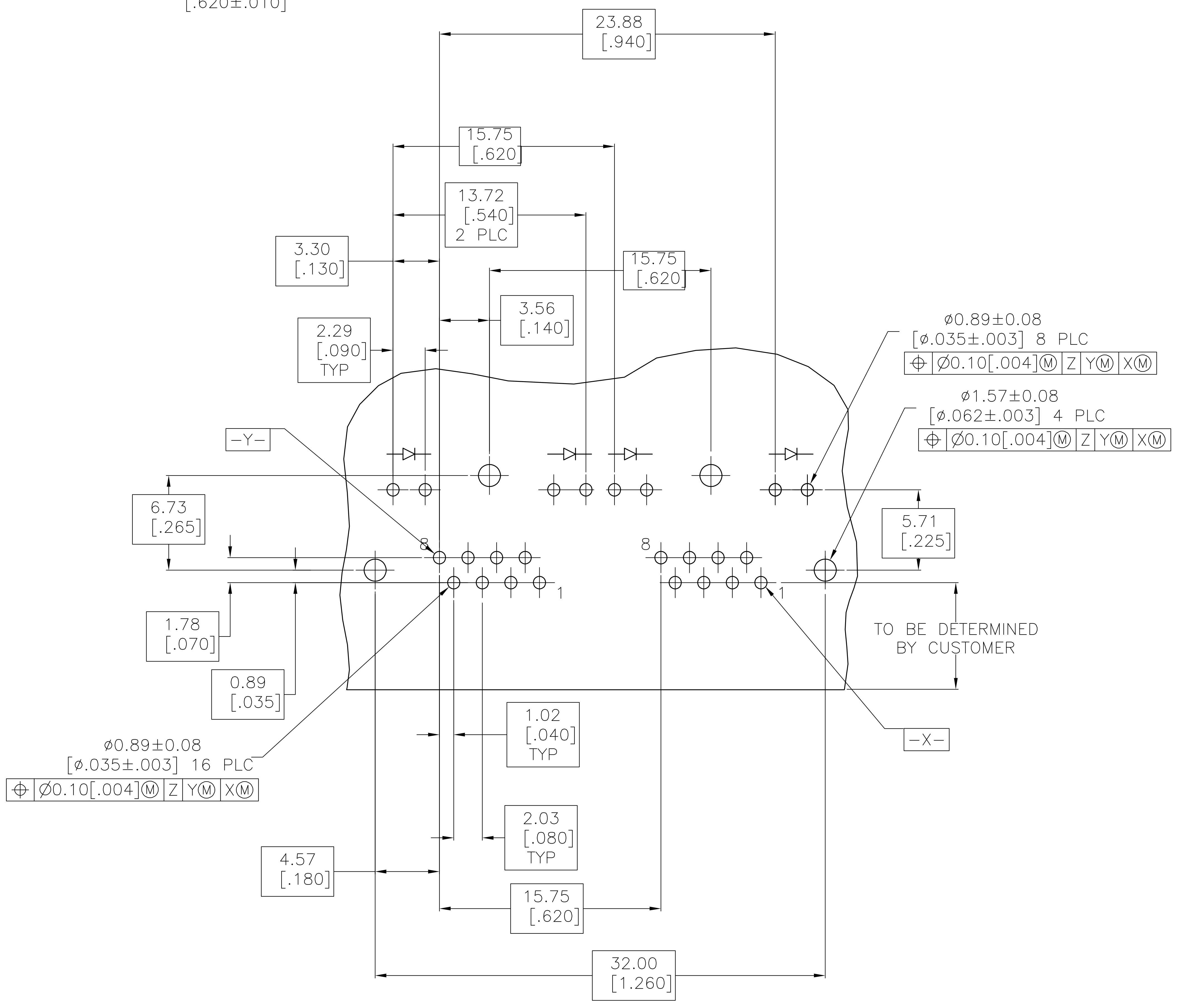
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

LOC	DIST	REVISIONS				
AA	00	LTR	DESCRIPTION	DATE	DWN	APVD
		C	ECO-07-022131	02NOV07	LAM	JW





1. MATERIAL:
   HOUSING – HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK, UL94V-0
   TERMINALS – 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81μm[.000150] MIN THICK BRIGHT TIN LEAD IN SOLDER AREA, 1.27μm[.000050] MIN GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27μm[.000050] MIN THICK NICKEL.
   SHIELD – 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27μm[.000050] MIN SATIN NICKEL WITH 2.03μm[.000080] MIN TIN POST DIPPED ON PCB GROUND TABS
   LIGHT EMITTING DIODE (LED) – DIFFUSED EPOXY LENS, 0.51 X 0.51[.020 X .020] CARBON STEEL WIREFRAME LEADS PLATED WITH 8.89μm[.000350] TIN/COPPER OVER 2.03μm[.000080] SILVER OVER 1.02μm[.000040] NICKEL UNDERPLATE OVER 2.03μm[.000080] COPPER UNDERPLATE
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIIONS PART 68, SUBPART F.
3. SUGGESTED PANEL OPENING DIMENSIONS.
4. SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
5. SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
COMPONENT SIDE

GREEN	GREEN	1364173-5
YELLOW	GREEN	1364173-1
POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR FOR EACH HOUSING		

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC	± -
1 PLC	± -
2 PLC	± 0.25[.01]
3 PLC	± 0.13[.005]
4 PLC	± -
ANGLES	± -

MATERIAL: SEE NOTE 1
FINISH: SEE NOTE 1

DWN M.MORRIS 08JAN00
CHK D.DIXON 08JAN00
APVD D.DIXON 08JAN00
PRODUCT SPEC 108-1163-4
APPLICATION SPEC 114-2154
WEIGHT -

Tyco Electronics
Tyco Electronics Corporation
Harrisburg, PA 17105-3608

NAME
INVERTED MODULAR JACK ASSEMBLY,
1X2, PANEL GROUND, SHIELDED,
NO MOUNTING LEGS, WITH LEDS

SIZE A1 CAGE CODE 00779 DRAWING NO C-1364173 RESTRICTED TO -

CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV C